

LTM4623 25LD-BGA-PBF 6.25mm X 6.25mm X 2.42mm (TABLE OF MATERIAL DECLARATION)											
This Package is RoHS compliant per EU RoHS Directive 2003/95/EC.											
It contains less than 100ppm cadmium (Cd) and less than 1,000ppm of each - lead (Pb), mercury (Hg), hexavalent chromium (Cr+), polybrominated biphenyl (PBB) and polybrominated diphenyl ether (PBDE)											
No.	Part Name	Material Name	Component Weight (gram)	Materials Analysis (element)	CAS Number	Material Mass (gram)	Materials Analysis (weight %)				
1	Substrate	Circuit Board	0.0362	Barium Compounds	7727-43-7	0.00102	2.81				
				Bismaleimide/Triazine Resin/Filler Substances (Silica Crystalline)	105391-33-1 1156-51-0/9003-36-5/21645-51-2	0.01006	27.77				
				Copper Metal	*non-disclosure 7440-50-8	0.01403	38.73				
				Copper Compounds	7440-14-8	0.00001	0.02				
				**Ecotoxic substances	7440-38-2 7440-28-0	0.00000	0.00				
				Gold metal or alloy	7440-57-5	0.00009	0.25				
				Nickel	7440-02-0	0.00071	1.95				
				Zinc	7440-66-6	0.00001	0.03				
				Continuous Filament Fiber Glass	65997-17-3	0.00791	21.82				
				Acrylic Resin	*non-disclosure	0.00192	5.31				
				Epoxy Resin	*non-disclosure	0.00007	0.19				
				Chromium(III) oxide	1308-38-9	0.00000	0.00				
				Silica amorphous	7631-86-9	0.00010	0.27				
				Talc;not containing fibers like asbestos	14807-96-6	0.00012	0.32				
				Aromatic carbonyl compounds	non-disclosure	0.00011	0.30				
				Cyanoguanidine	461-58-5	0.00000	0.01				
				Calcium caobonate	471-34-1	0.00001	0.04				
				Amine compounds	*non-disclosure	0.00002	0.05				
				Leveling agent and others	*non-disclosure	0.00005	0.13				
				2	Solder Paste	Alloy	0.0039	Sn	7440-31-5	0.00374	95.00
								Sb	7440-36-0	0.00020	5.00
				3	Passive/Active Components		0.0520	Iron Powder (Fe)	7439-89-6	0.03603	69.28
								Copper (Cu)	7440-50-8	0.01077	20.71
Nickel (Ni)	7440-02-0	0.00062	1.19								
Tin (Sn)	7440-31-5	0.00045	0.86								
Ceramic (Ba) Compounds	12047-27-7	0.00414	7.95								
4	Active Ics	Silicon	0.0016	Silicon	7440-21-3	0.00161	100.00				
5	Wire	Gold	0.0007	Au	7440-57-5	0.00067	99.99				
6	Solder Ball	SAC305	0.0420	Sn	7440-31-5	0.04048	96.5				
				Ag	7440-22-4	0.00126	3				
				Cu	7440-50-8	0.00021	0.5				
7	Encapsulation	Epoxy Resin	0.0804	Fused Silica	60676-86-0	0.06207	77.20				
				Epoxy Resin	non-disclosure	0.00716	8.90				
				Phenol Resin	non-disclosure	0.00716	8.90				
				Crytalline Silica	14808-60-7	0.00241	3.00				
				Carbon Black	1333-86-4	0.00040	0.50				
				Metal Hydroxide	non-disclosure	0.00121	1.50				
Total Package Weight			0.2168								

Note: Composition derived from MSDS and material C of C from Vendors  
 Component Weight based on assembly of generic parts